

IN THE CLAIMS:

Amend claim 1 as follows:

--1. (amended) A plasma CVD apparatus comprising a substrate processing zone with a deposition substrate area disposed therein, a plasma generating zone for generating plasma of a first gas, and a plasma confining electrode for separating the substrate processing zone and the plasma generating zone and confining the first gas and having holes for passing the first gas containing neutral radicals from the first gas plasma, wherein

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the plasma confining electrode has a hollow structure, accommodates horizontal gas dispersing plates within the hollow structure for uniformizing a second gas in the plasma confining electrode, and has holes for introducing the second gas into the substrate processing zone to form a desired film on a deposition substrate located on the deposition substrate area by gas phase chemical reaction of the first gas containing neutral radicals and the second gas with each other; and

the vertical distance between the plasma confining electrode and the deposition substrate is no longer than 1,500 times the mean free path λ_g of a blend gas of neutral radicals and the second gas in the substrate processing zone at the time of film formation.--

Amend claim 4 as follows:

--4. (amended) A plasma CVD apparatus comprising a substrate processing zone with a deposition substrate area disposed therein, a plasma generating zone for generating plasma of first gas, and a plasma confining electrode for separating the substrate processing zone and the plasma generating zone and confining the first gas and having holes for passing first gas containing neutral radicals from the first gas plasma, wherein

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the plasma CVD apparatus further comprises a gas introducing member disposed between the plasma confining electrode member and the deposition substrate and having a plurality of holes, through which a second gas is introduced into the substrate processing zone to form a desired film on a deposition substrate by gas phase chemical reaction between the first gas containing neutral radicals and the second gas; and

the gas introducing member has a hollow structure, accommodates dispersing plates within the hollow structure for uniformizing the second gas in the gas introducing member and is vertically spaced apart by a distance no longer than about 1,500 times the mean free path λ_g in the substrate processing zone.--

REMARKS

The application has been amended so as to place it in condition for allowance at the time of the next Official Action.

Claims 1-2 and 4-5 are pending.